Satellite Projects by Antarikchya Pratisthan Nepal [Space Foundation Nepal]







Eliza Sapkota Satellite Research Fellow Antarikchya Pratisthan Nepal

Antarikchya Pratisthan Nepal [APN]





"Vision 2050: a vision to launch Nepal's First Astronaut in Space by 2050"





"Train space engineers and R&D in space technology in Nepal"

Next Generation Space Tech Engagement Program





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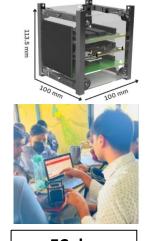


Grade 3-7



PaperSat Art Program

Grade 6-10



ECube

Grade 7-12



SastoCube Satellite Program

Grade 11-12



1st High School CubeSat

NepaliSat-1 BIRDS-3

Science, Technology, Innovation and Capacity-Building in Nepal through PHI



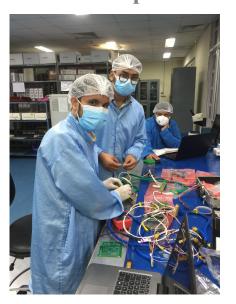
"Train and develop space engineers and in house space facilities in Nepal"



Ground Station Operation at NAST



Antenna Lab Development at Khwopa Eng. College



Satellite Testing Lab at India



Satellite Research Fellow at GS antenna maintenance at **NAST**



Antarikchya Pratisthan Nepal

Space Projects

- Danfe
- Munal
- Danfe-II [PHI-1]

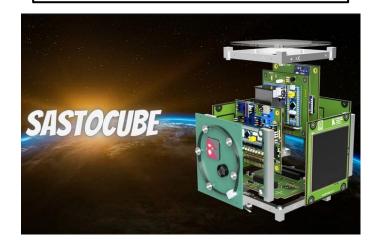






Education Programs

- PaperSat
- E-Cube
- SastoCube



MUNAL

High School Satellite Consortium



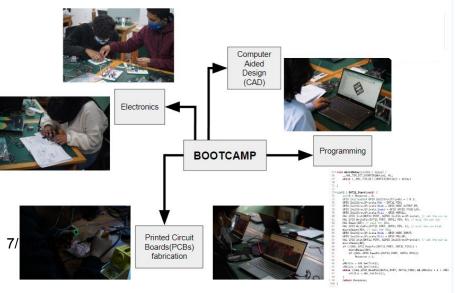


High School Satellite: MUNAL



• 9 High School Students (KUHS and Government School)

• To be launched on August 2023













Project MUNAL



Objectives:

• In house design, build, test and launch of Nepal's first High School CubeSat

To demonstrate novel SPDM based COM/OBC designed in-house

 To give continuity and improvement to two Missions of NepaliSat-1: Store & Forward (S&F) and Imaging Mission

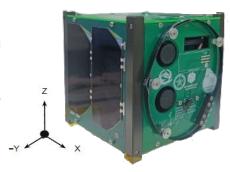
Specifications		
Dimension	1U (100X100X113.5) mm	
Weight	1.051 kg	
Harness	Backplane Board	
Missions	Camera, PACDS, SPDM, Art mission	

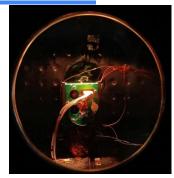
OBC : On-Board Computer EPS : Electrical Power Supply

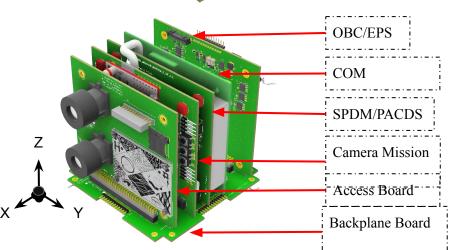
SPDM : Satellite System on Chip Payload Demonstration

Mission

PACDS: Passive Attitude Control and Determination System









BPB: Backplane Board

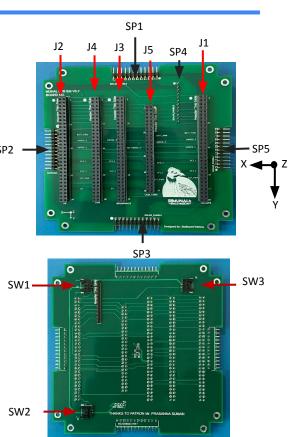


- 60 pin connectors are used for all the mission boards and EPS/OBC.
- 50 pin connector for COM board (Reference: Addnics COM board ICD)



Boards placement on BPB

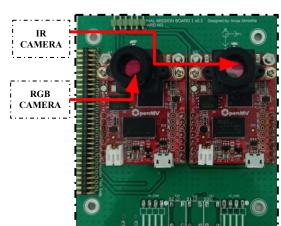
Connector Name	No. of Pins	Description
J1-J4	60	OBC/EPS, AB, SPDM/PACDS, CAM
J5	50	COM Board
SP1-SP4	12	Solar Panels
SP5	12	Antenna Panel
SW1-SW3	2	Deployment switch

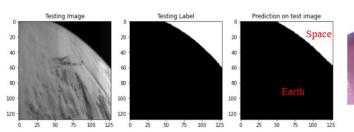




CAM: Camera Mission









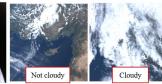


Image Classification

Image Segmentation

E444000				
Feature	Specification			
Cameras	OpenMV H7 Plus (RGB & NIR)			
Ground Swath	168*95 km (550km orbit)			
Ground Sampling Distance	131m			
Resolution	1280x720			







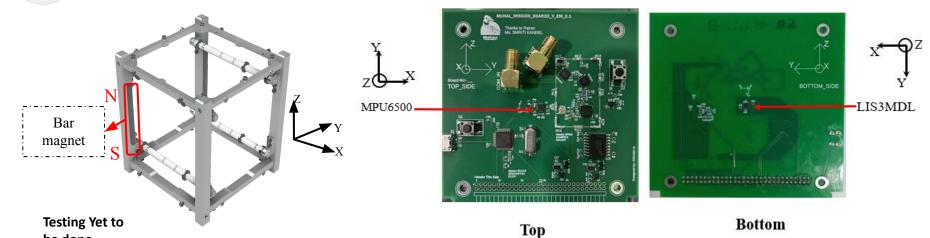
RGB Image

IR-Image



PACDS: Passive Attitude Control and Determination





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*Reference: BIRDS-5 ADCS Design

BIRDS Open-Source

Hysteresis Rod (on Bottom Solar Panel on Bottom Surface)

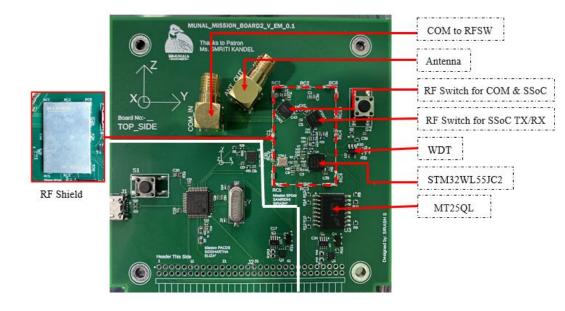
Bar Magnet	4*4(each rail)	AlNiCo 5
Hysteresis Rod	8	HyMu80



SPDM: Satellite System-on-Chip Payload Demo

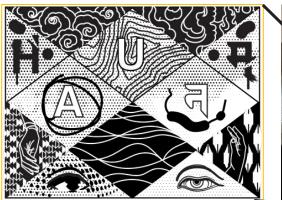


- Demonstrate the use of integrated Communication(COM) and On-Board Computer(OBC) subsystem based on novel SSoC for future cubesat missions using LoRa(Long Range) Modulation.
- ARM based Dual Core Processor with Radio
- +22 dBm Transmitting power
- -148 dBm Receiving sensitivity



Art and Culture Mission

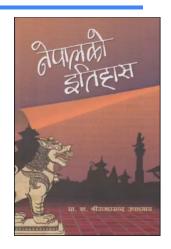


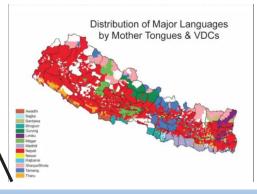














Danfe Space Mission

Multi Payload CubeSat Platform (MPCP)









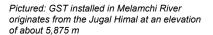


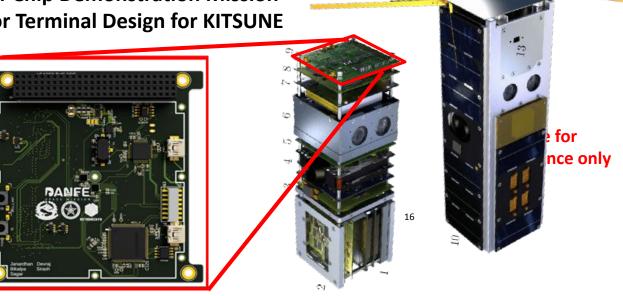
Overview



- **MCPC 3U Satellite for Mission Demonstration**
- **PX4 Demonstration Mission**
- **Satellite System-on-Chip Demonstration Mission**
- **Also Ground Sensor Terminal Design for KITSUNE**







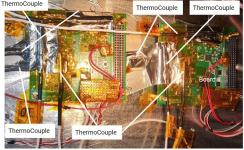
Source: Aalto-1, multi-payload CubeSat: Design, integration and launch

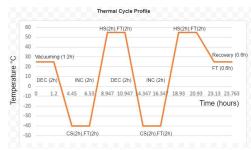


Space Qualification Test

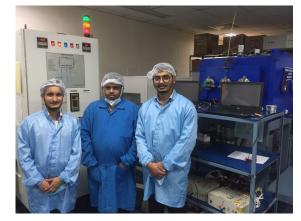








Thermal Vacuum Test at Centum Electronics, Bangalore, India



Thermal Vacuum Test at Centum Electronics, Bangalore, India



Electromagnetic Compatibility Test at Khwopa Engineering College, Bhaktapur, Nepal

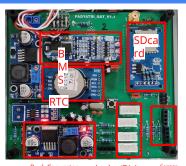


GST Design and Uplink Test





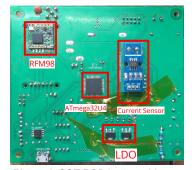




Analog/Digit al I/os
Pictured: GST PCB top side



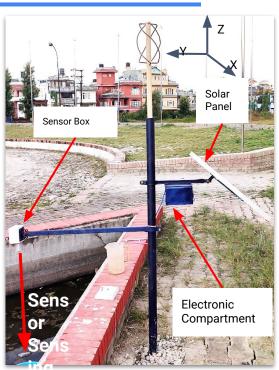
Pictured: GST battery pack



Pictured: GST PCB bottom side



Pictured: Temperature humidity sensor and ultrasonic sensor



Long Duration test of GST Installed at NAST

In house Design of GST for Flood Early warning System



KITSUNE GST Installation for Flood Warning in Melamchi Municipality [Rural area]

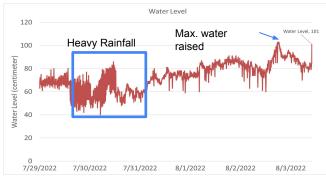








GST Melamchi River Data











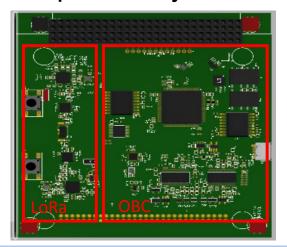
Danfe-2



- UNOOSA's Access to Space for all: Payload Hosting Initiative project.
- MBRSC'S 12U satellite: (PHISat)
- Munal's OBC/EPS and Danfe Space Mission in a single board. (Modular Design)

 Integrated OBC, EPS and Communication system (Bus system in a single board)

• PDR completed on May 9

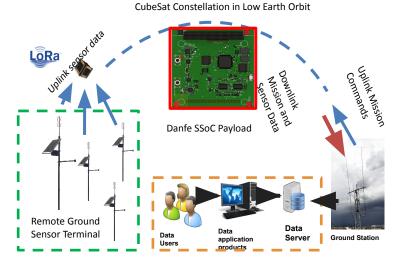




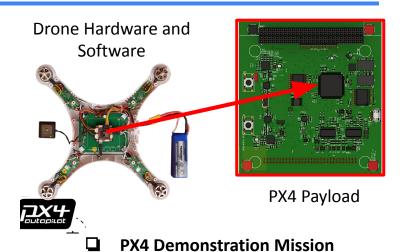
PHI-I APN LoRa Payload [Danfe-2)



 Nepal's Payload hosted by 12U MBRSC Satellite PHISat



Satellite System-on-Chip Demonstration Mission











"Design a payload for CubeSat which contributes in next-generation capacity building for in-house satellite development in Nepal"

Antarikchya Educational Programs



PaperSat



Satellite Bootcamp





PaperSat Space Art Comp







Localized CanSat Training (UNISEC Derived Concept)









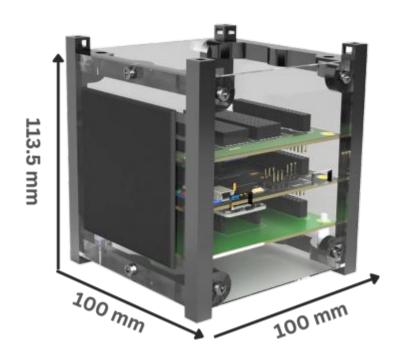
CanSat training provided at Budhanilkantha School

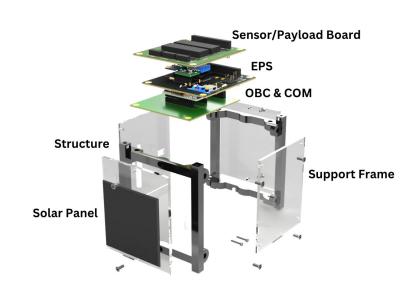




E-Cube

Educational Kit to educate young students about Satellite Systems



















E-Cube An Educational Satellite

E-Cube









Satellite technology has revolutionized the way we live, work, and communicate. From weather forecasting to navigation, from communication to disaster management, satellites have become an indispensable part of our daily lives. However, despite their ubiquitous presence, the technology behind these satellites remains a mystery to next generation of innovators, we propose the Satellite BootCamp, a comprehensive hands-on training program that provides participants with a thorough understanding of small satellite design and system engineering. Through intensive practical lessons, participants will learn the skills and knowledge necessary to design, develop, and test their own functional small satellites













Printing







Wireless Hardware Analytics

Presentation







BRIHASPATI '17

STUDENTS



IMPACT

I HAD TAKEN TRAININGS

FROM OTHER

ORGANIZATIONS BUT

NOTHING CAME CLOSE TO

ANTARIKCHYA'S PROGRAMS

WHICH USES SPACE

TECHNOLOGY AS A TOOL TO

TEACH CIRCUITRY.

ELECTRONICS.

PROGRAMMING AND DESIGN

IN A MORE HANDS-ON

METHOD. VERY UNIQUE.

NABIN KANDEL
SATELLITE BOOTCAMP BATCH I





1. Design Process

⊜

17 PARTNERSHIPS

*

CAD

AUTABIKCHAA

CAD (Computer-Aided Design) is the use of com-CAD (Computer-Adea Design) is the use of com-puter-based software to aid in design processes. CAD software is frequently used by different types of engineers and designers. CAD software can be used to create two-dimensional (2-D) drawings or three-dimensional (3-D) models which makes the user easier to visualize digitally.

PCB

Printed circuit board (PCB) design brings your elec-tronic circuits to life or in its physical form. PCB design software makes it easier to define stable electrical connectivity between the components placed on manufactured board.

2. Manufacturing 3D Printing

3D printing or additive manufacturing is a process in which the originally gener

Soldering

PCB Manufacturing

Soldering is a process in which two or PCB manufacturing is the process or procedure more items are joined by melting and that transforms a circuit board design into a physical structure based upon the specifications provided in the design package. This physical manifestation is achieved through the following actions or techniques: Imaging desired layout on copper clad laminates

3. Building a Satellite Introduction to satellite

Assembling a Satellite

The satellite that we are building is CubeSats. They are also of different types, among them we are building IU. CubeSats A U is a lOxIOxIO cm cube of space from which CubeSats derive their name and can have 1.33 kg of weight for every U in their structure.

Programming a Satellite

4. Satellite Mission

We use off-sell components and systems to make a satellite. A particular design pro-cess is followed starting from basic integration to complete satellite integration. And as a result you will make complete IV satellite.

Programming is one of the key factor to run and operate satellite, here you will

program each sensors(Payload) in the satellite and at the end you will create a program to acquire a data from satellite to ground station.

Satellite Mission Discussion

Satellite missions are inspired by different climates i.e. Global warming, GLOF, Climate Change, etc. we will discuss on what a Satellite mission should be to observe such climates and find the satellite's pur-

Satellite Mission Implementation

From different mission ideas previously brainstromed, here we decide one of the mission ideas as our main mission Following the step, previously decided mission idea will then be implemented into the satellite. Implementation phase can be considered as the most intriguing phase as one can implement their formerly learnt skills like CAD modeling. PCB design, Soldering, 3D printing. This will result in satellit payload with properly implemented mission on it.

Mission Presentation

We will have presentation and discussion on what has We will have presentation and discussion on what ha been obtained, executed and implemented till now. As well as the expertiss review of the work and sug-gestion to make the satellite design process successful and a properly functioning satellite as a result.

CANSAT BOOTCAMP (TRAINING)**











ElectronicsSoldering







Wireless Hardware Analytics/

Presentation









Ju priming or adouter manufacturing is a process in which me originally generated CAD model is constructed into a three dimensional object layer-by-layer. 3D printing can be done in a variety of processes in which material is deposited, joined or solidified under computer control, with material being added together to get the desired 3-D output.

more items are joined by melting and putting a filler metal into the joint, the filler metal having a lower melting point than the adjoining metal. Unlike welding, soldering does not involve

ANTARIKCHYA IS TRAINING NEXT GENERATION SPACE LEADERS



MELAMCHI '22